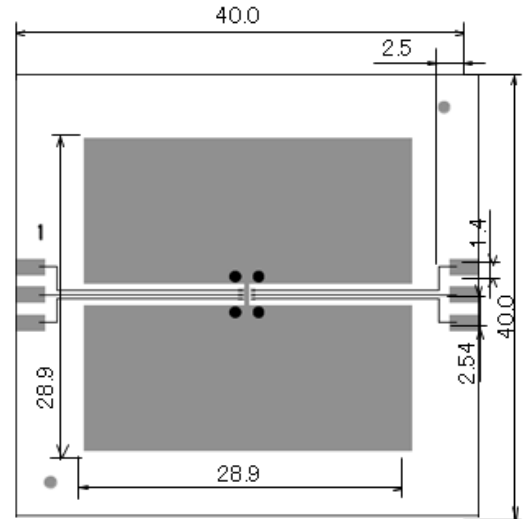


● DFN1515-6A Power Dissipation

Power dissipation data for the DFN1515-6A is shown in this page.  
 The value of power dissipation varies with the mount board conditions.  
 Please use this data as the reference data taken in the following condition.

1. Measurement Condition

- Condition : Mount on a board
- Ambient : Natural convection
- Soldering : Lead (Pb) free
- Board Dimensions : 40 x 40 mm (1600mm<sup>2</sup> in one side)
- Metal Area : 1st Meter layer about 50%
- : 2nd Inner Metal layer about 50%
- : 3rd Inner Metal layer about 50%
- : 4th Metal layer about 50%
- : Each heat sink back metal is connected to the Inner layers respectively.
- Material : Glass Epoxy (FR-4)
- Thickness : 1.6 mm
- Through-hole : 4 x 0.8 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (T<sub>j</sub> max = 125°C)

Ambient Temperature(°C)	Power Dissipation Pd(mW)	Thermal Resistance (°C/W)
25	800	125.00
85	320	
125	0	

